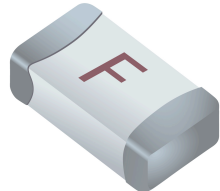


MATERIAL DECLARATION SHEET



Material Number	SF-1206SPxxxM			
Product Line	Lead Free Multilayer Time Lag Chip Fuse			
Compliance Date	08/30/2017			
RoHS Compliant	YES	MSL	1	

No.	Construction Element (subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ceramic Body	Glass Ceramic	11.5212	Boron	7440-42-8	7.39%	6.1943%	83.822%
				Carbon	7440-44-0	2.11%	1.7687%	
				Aluminum	7429-90-5	18.65%	15.6327%	
				Silicon	7440-21-3	15.24%	12.7742%	
				Potassium	7440-09-7	0.53%	0.4445%	
				Oxygen	7782-44-7	56.08%	47.0072%	
2	Termination	Silver with Glass	1.4333	Silver	7440-22-4	92.25%	9.6574%	10.428%
				Oxygen	7782-44-7	2.23%	0.2216%	
				Zinc	7440-66-6	1.64%	0.1635%	
				Silicon	7440-21-3	0.10%	0.0096%	
				Bismuth	7440-69-9	3.78%	0.3759%	
3	Fuse Link	Silver	0.0941	Silver	7440-22-4	100%	0.6846%	0.685%
4	Plating	Nickel	0.6057	Nickel	7440-02-0	100.00%	1.9789%	4.407%
		Tin		Tin	7440-31-5	100.00%	2.4278%	
				Oxygen	7782-44-7	50.86%	0.0250%	
				Aluminum	7429-90-5	16.02%	0.0079%	
				Silicon	7440-21-3	18.74%	0.0092%	
				Potassium	7440-09-7	0.57%	0.0003%	
				Zinc	7440-66-6	9.82%	0.0048%	

MATERIAL DECLARATION SHEET



6	Masking Layer	Glass Ceramic	0.0838	Iron	7439-89-6	3.99%	0.0020%	0.609%
				Boron	7440-42-8	9.83%	0.0600%	
				Carbon	7440-44-0	1.81%	0.0110%	
				Aluminum	7429-90-5	16.85%	0.1028%	
				Silicon	7440-21-3	15.58%	0.0950%	
				Potassium	7440-09-7	0.53%	0.0032%	
				Oxygen	7782-44-7	55.40%	0.3379%	
Total weight	13.7448							

This Document was updated on: 8-30-17

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.